

A 2.125 Gbaud $1.6\text{k}\Omega$ Transimpedance Preamplifier in $0.5\mu\text{m}$ CMOS

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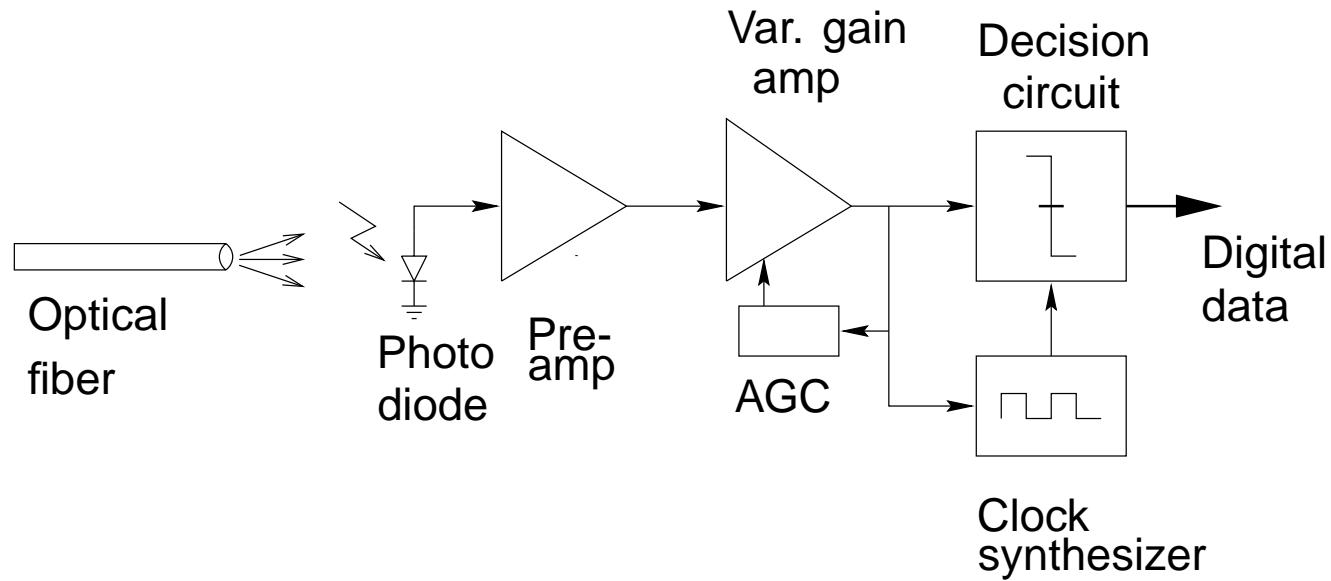
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OUTLINE

- Motivation
- Shunt-peaked Amplifier
- Inductor Modeling and Optimization
- Circuit Layout and Measurement
- Summary

SYSTEM OVERVIEW



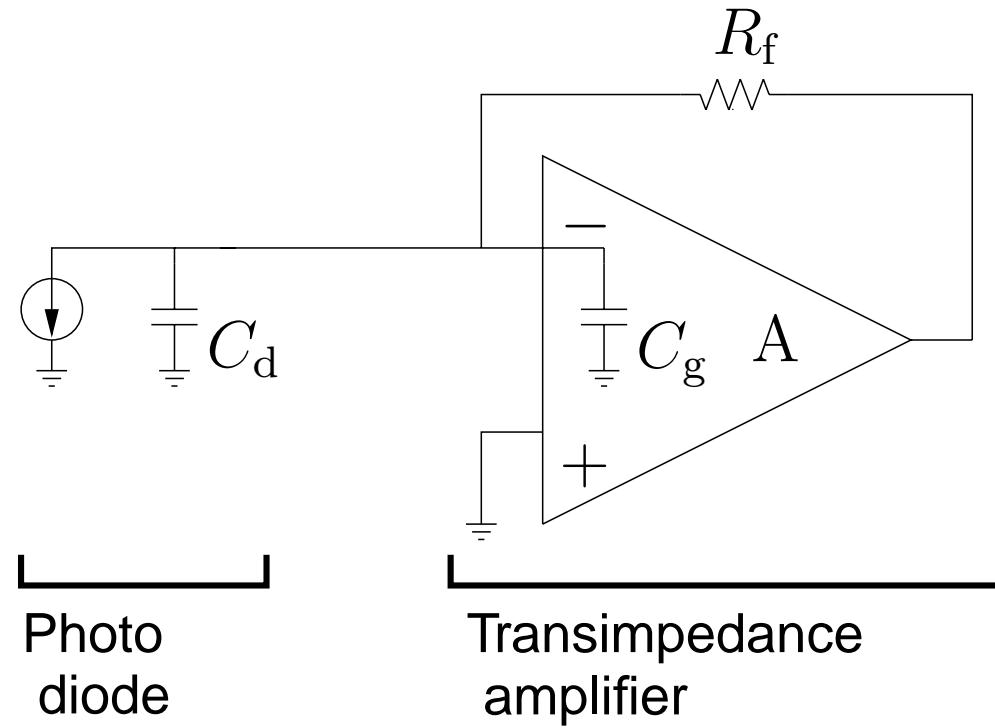
- Pre-amp design is critical
- Challenge: CMOS implementation

CMOS vs. GaAs

Factor	GaAs	CMOS
Performance	Excellent	Sufficient for up to low GHz
Integration	Photodiode with Pre-amp	Analog and Digital
Cost	High	Low

- Photodiode in GaAs
- Flip-chip techniques can reduce parasitics at the GaAs to CMOS transition
- Parasitic coupling from digital to analog is a challenge for integration

TRANSIMPEDANCE AMPLIFIER

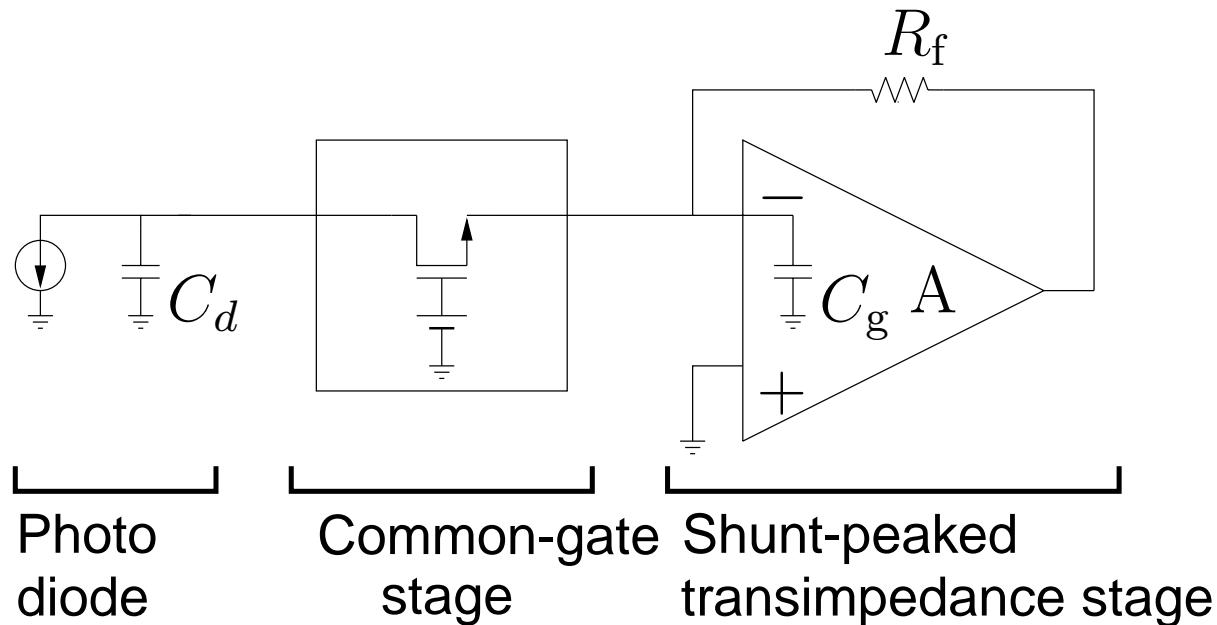


- $\omega_{3\text{dB}} = \frac{1}{R_{\text{in}}C_{\text{in}}} = \frac{(A+1)}{R_f(C_d+C_g)} \approx \frac{A}{R_f(C_d+C_g)}$
- $A_{\text{MAX}} = k \frac{\omega_T}{\omega_{3\text{dB}}}$ where ($k \approx 1$)

TRANSIMPEDANCE LIMIT

- $R_{f,MAX} \approx \frac{k\omega_T}{\omega_{3dB}^2(C_d+C_g)}$
- Desire maximum R_f for sensitivity, stability and high gain
- Need to circumvent this limit

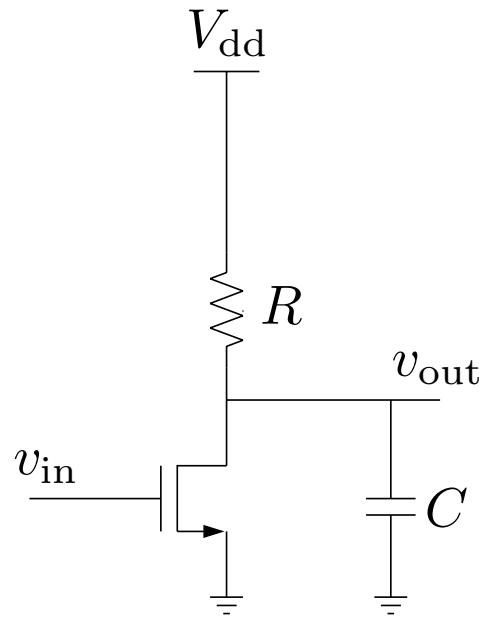
CIRCUMVENTING THE TRANSIMPEDANCE LIMIT



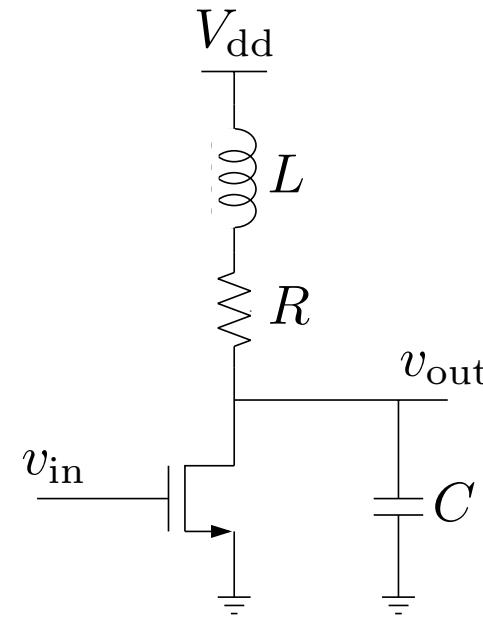
- Decouple photodiode from the transimpedance stage with common-gate stage
- Increase gain-bandwidth product by shunt-peaking

SHUNT-PEAKED AMPLIFIER

Common Source Amplifier



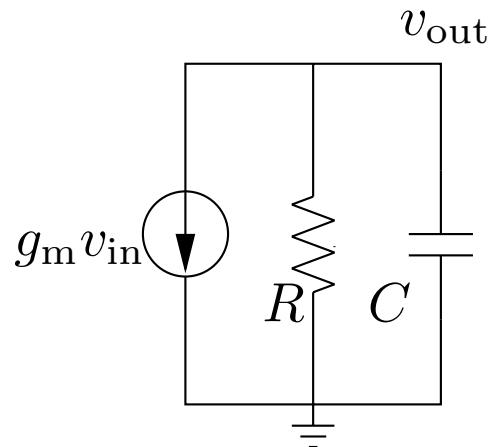
Shunt-peaked Amplifier



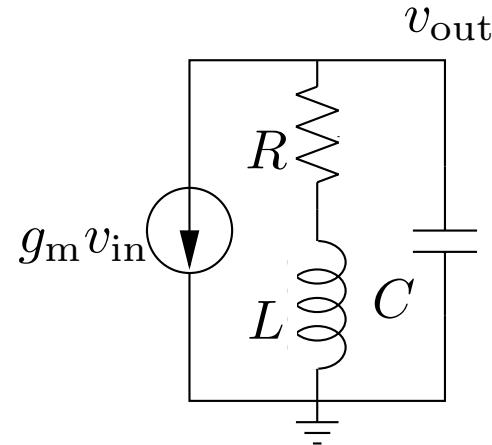
- Bandwidth enhancement using zeros
- No additional power dissipation

SMALL SIGNAL MODELS

Common Source Amplifier



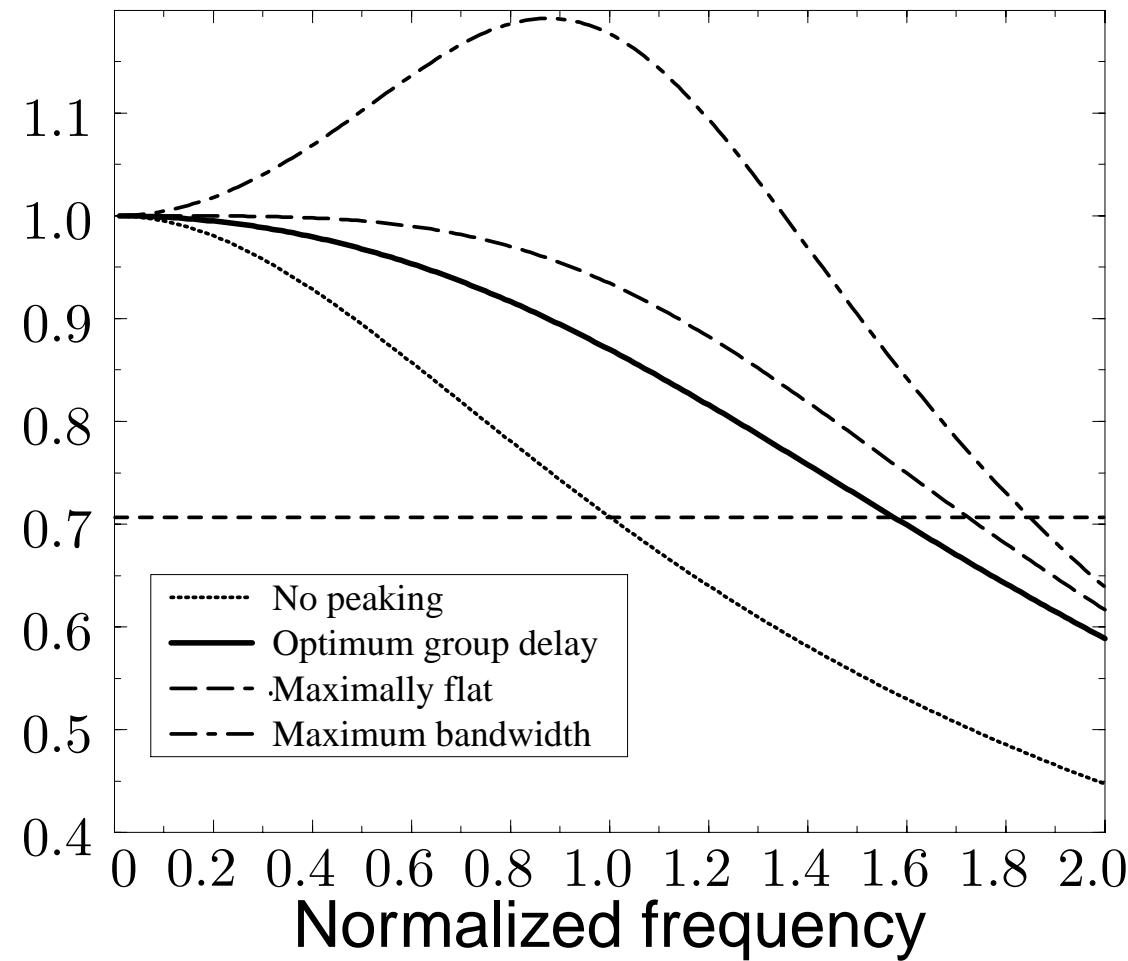
Shunt-peaked Amplifier



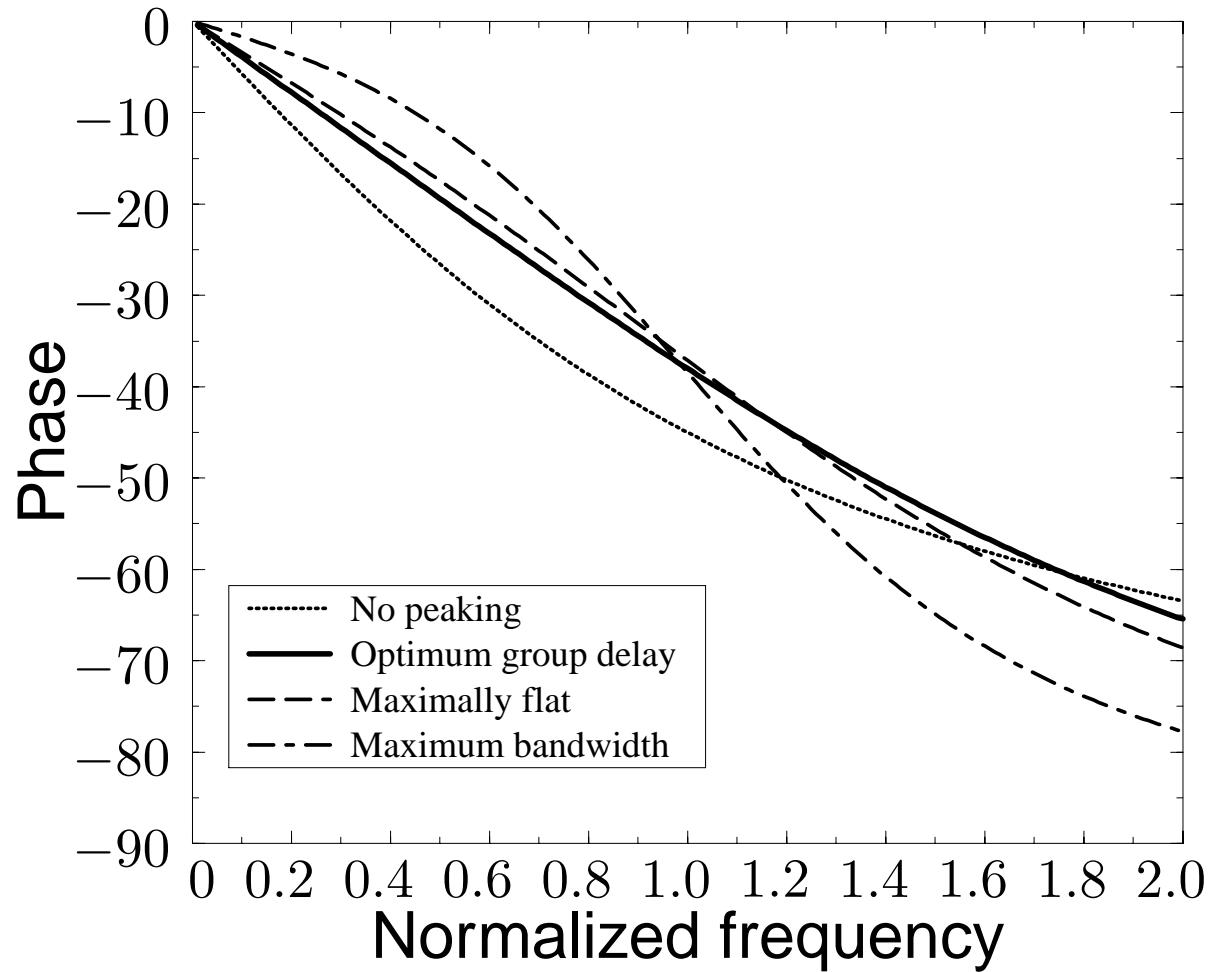
- One pole
- $\frac{v_{\text{out}}}{v_{\text{in}}}(\omega) = \frac{g_m R}{1+j\omega RC}$

- One zero, two poles
- $\frac{v_{\text{out}}}{v_{\text{in}}}(\omega) = \frac{g_m(R+j\omega L)}{1+j\omega RC-\omega^2 LC}$

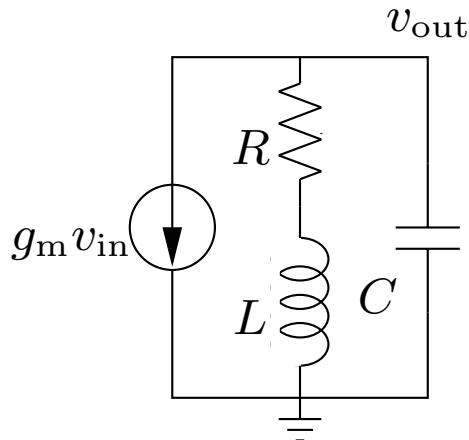
MAGNITUDE RESPONSE



PHASE RESPONSE



FREQUENCY RESPONSE

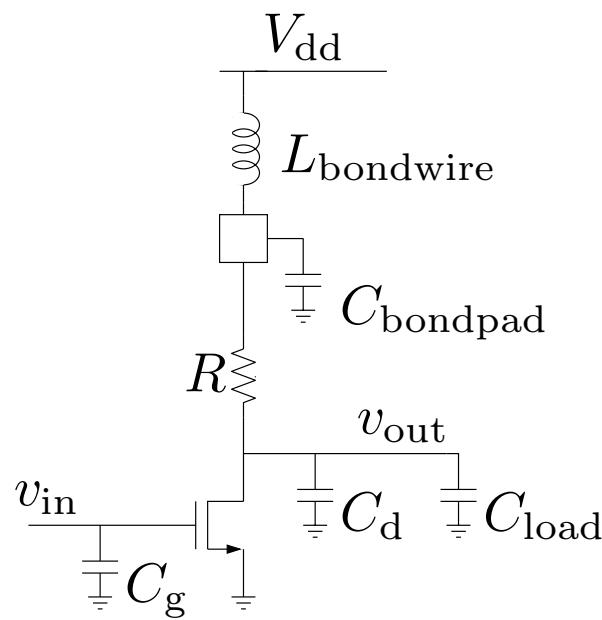


- Two time constants:
 $\tau_C = RC, \tau_L = L/R$
- Ratio determines performance:
 $m = \frac{\tau_L}{\tau_C} = \frac{L}{R^2 C}$

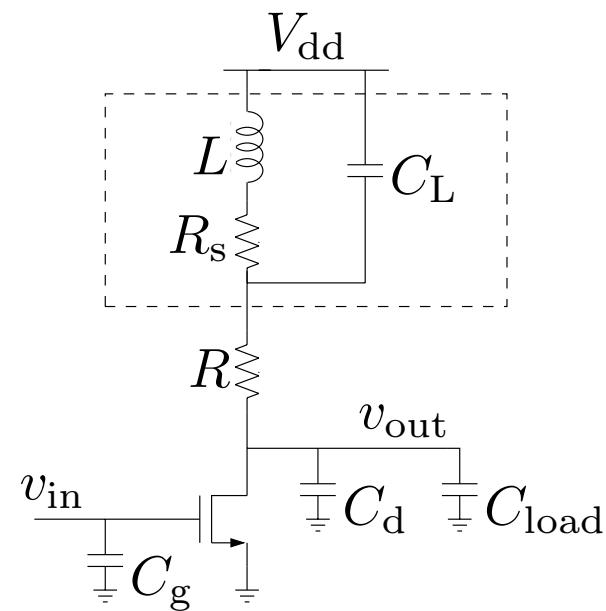
Factor (m)	Normalized ω_{3dB}	Response
0	1.00	No shunt peaking
0.32	1.60	Optimum group delay
0.41	1.72	Maximally flat
0.71	1.85	Maximum bandwidth

ON-CHIP SHUNT PEAKING : PREVIOUS WORK

Bond-wire inductor



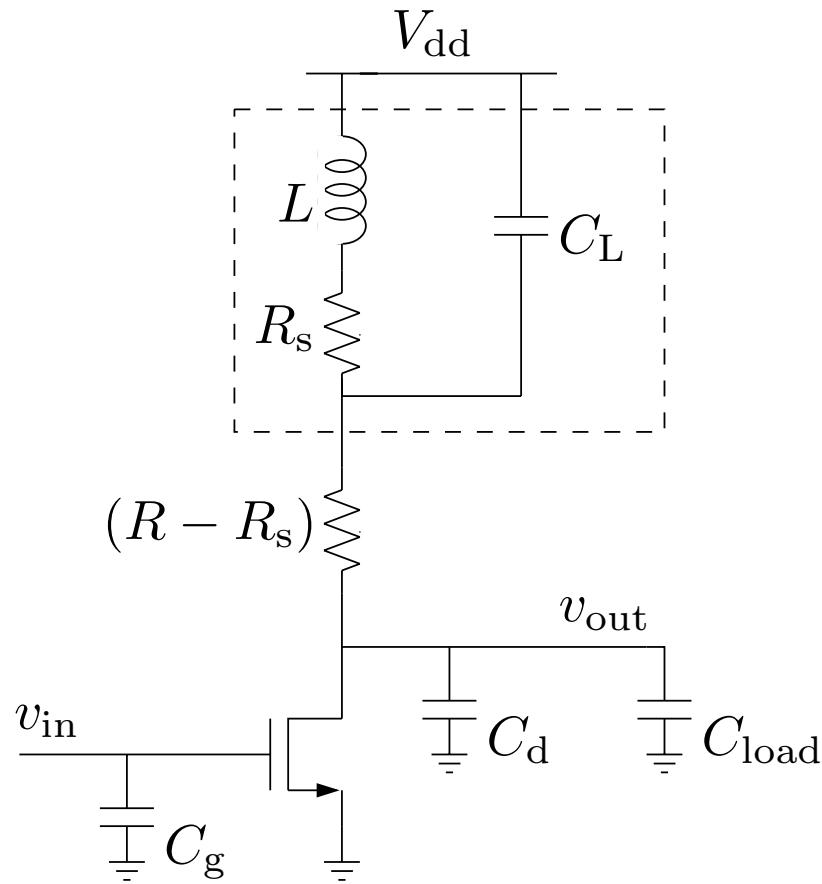
Maximum Q on-chip



- Large C_{bondpad}
- Limited L_{bondwire}
- Coupling issues

- Large C_L
- Large area
- Limited L

ON-CHIP SHUNT PEAKING: NEW



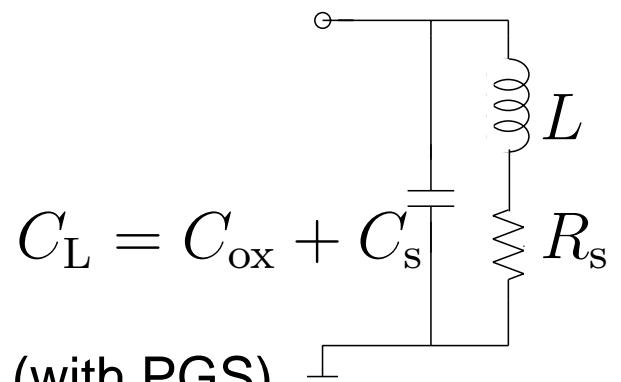
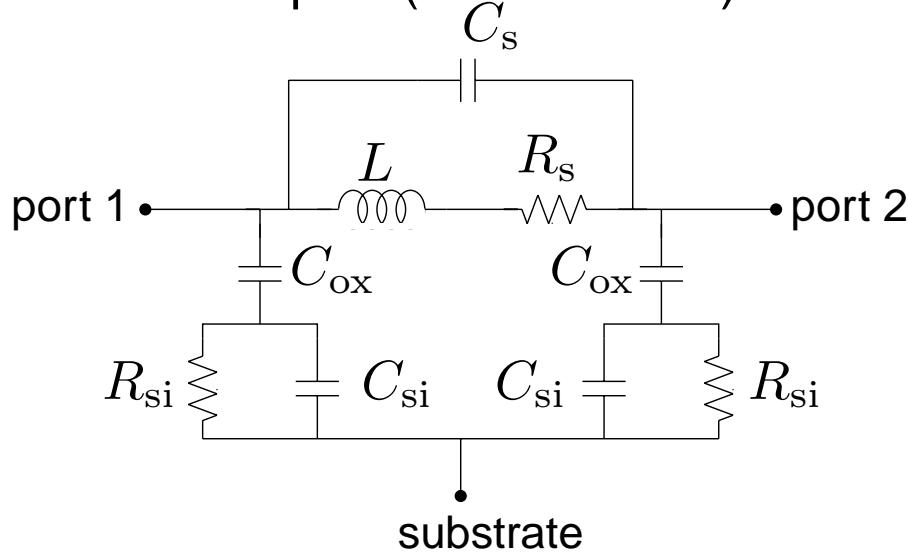
- Work with inductor parasitics
- R_s is **not** an issue
(now part of load resistance)
- Inductor Q is **not** relevant
- Minimize area and C_L
- L determined by
 R , C_{load} , C_L and C_d

MODELING CHALLENGE

- **Simultaneous optimization** of active and passive components
- 3-D field solvers are **inconvenient**
 - { Numerically expensive and cumbersome
 - { Good for **verification** but not for **design**
- **Scalable, analytical models**
 - { Design **guidelines** and explore **trade-offs**
 - { Circuit **design** and **optimization**

INDUCTOR MODELING

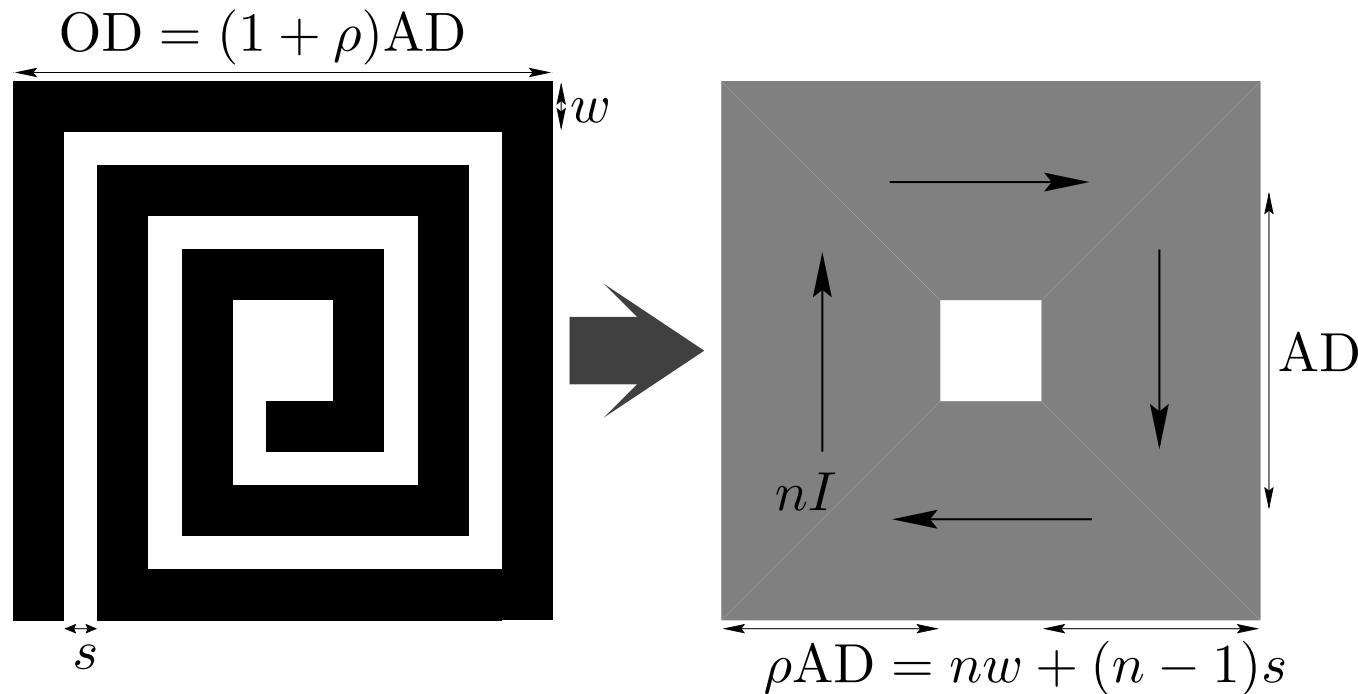
Two port (without PGS)



One port (with PGS)

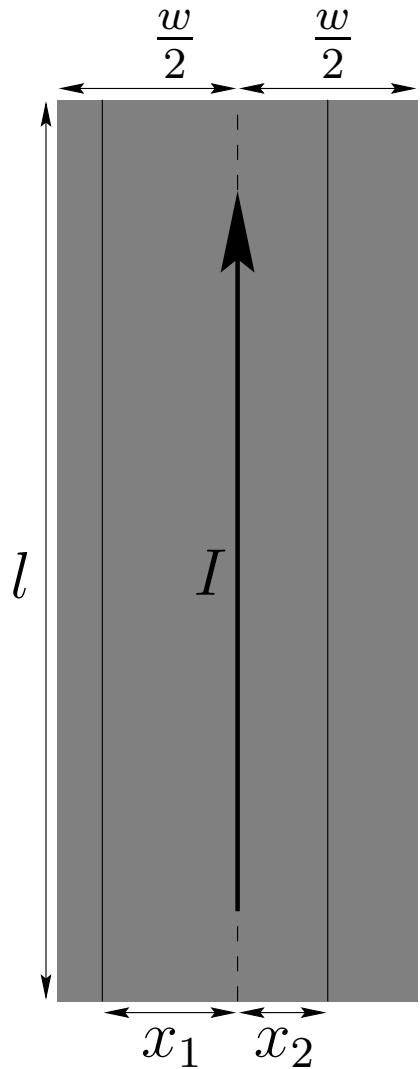
- Simple expressions for R_s , C_{ox} and C_s
- Patterned ground shield (PGS) eliminates R_{si} and C_{si}
- **NEED** simple, accurate expression for inductance!

CURRENT SHEET APPROACH



- Reduce complexity by $4n^2$
- Use symmetry
- Derive simple expression using GMD, AMD and AMSD

GMD, AMD AND AMSD



$$-\frac{w}{2} < x_1, x_2 < \frac{w}{2}$$

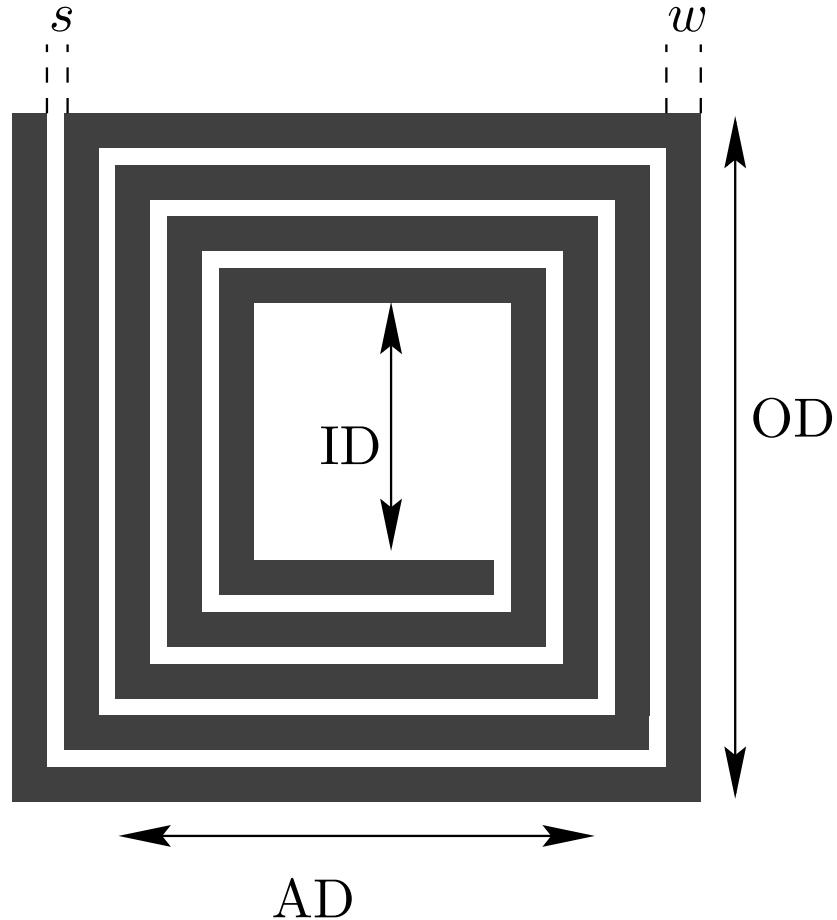
$$\ln(\text{GMD}) = \overline{\ln |x_1 + x_2|} = \ln w - 1.5$$

$$\text{AMD} = \overline{|x_1 + x_2|} = \frac{w}{3}$$

$$\text{AMSD}^2 = \overline{(x_1 + x_2)^2} = \frac{w^2}{6}$$

$$\begin{aligned} L &= \frac{\mu l}{2\pi} \left[\ln \left(\frac{2l}{\text{GMD}} \right) - 1 + \frac{\text{AMD}}{l} - \frac{\text{AMSD}^2}{4l^2} \right] \\ &= \frac{\mu l}{2\pi} \left[\ln \left(\frac{2l}{w} \right) + 0.5 + \frac{w}{3l} - \frac{w^2}{24l^2} \right] \end{aligned}$$

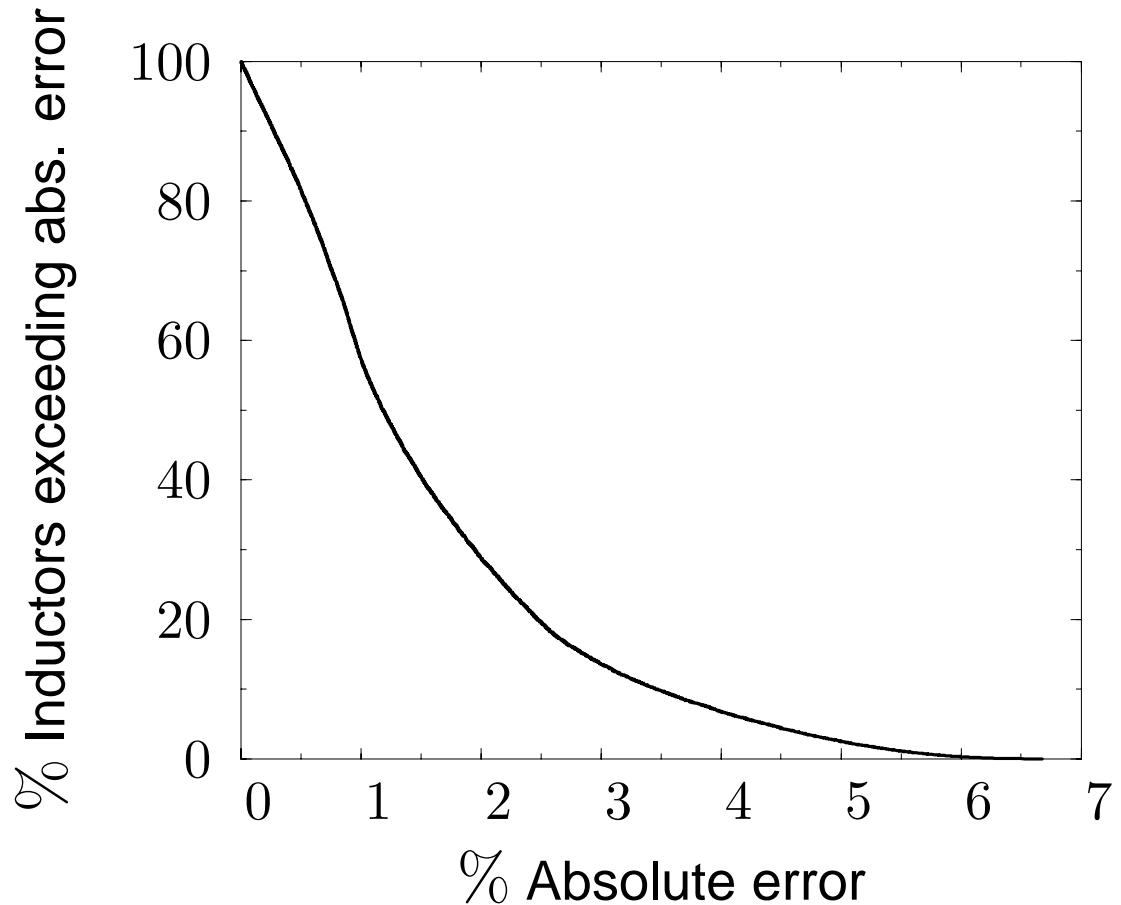
INDUCTANCE EXPRESSION



- $AD = 0.5(OD + ID)$
- $\rho = \frac{OD - ID}{OD + ID}$
- $\rho AD = nw + (n - 1)s$

$$\bullet L = \frac{2\mu n^2 AD}{\pi} \left[\ln \left(\frac{2.067}{\rho} \right) + 0.176\rho + 0.125\rho^2 \right]$$

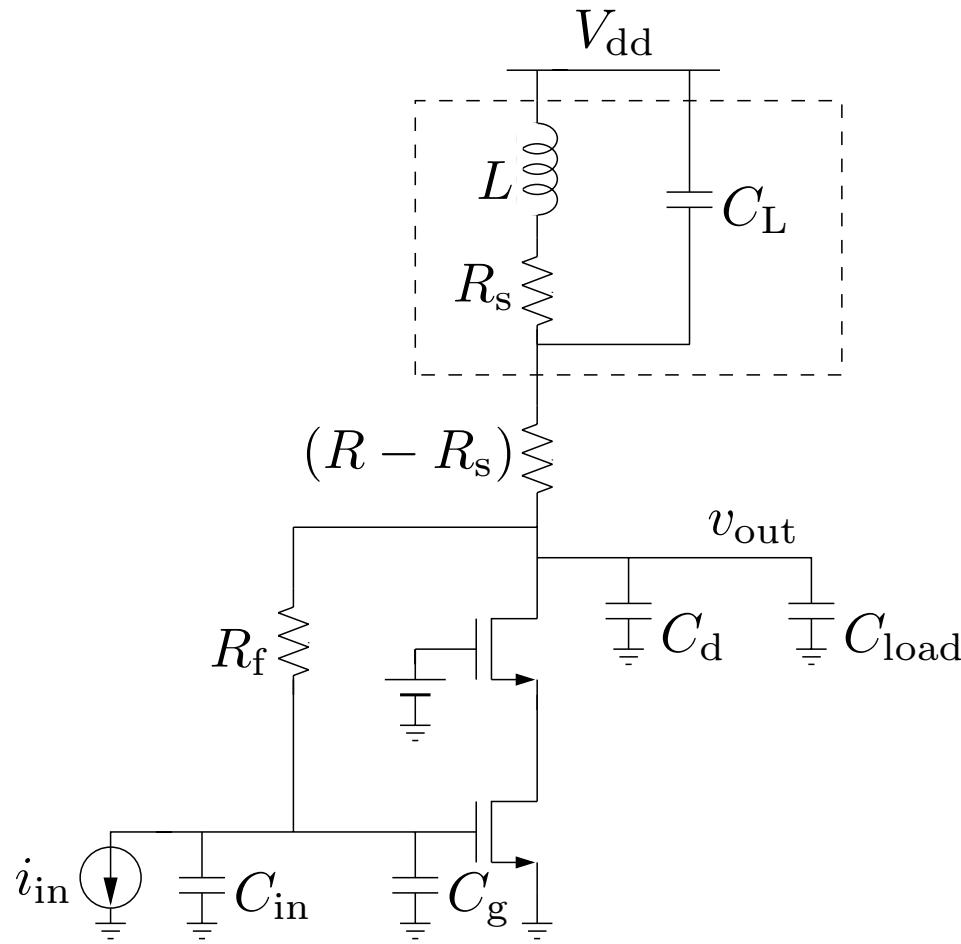
INDUCTANCE EXPRESSION



	Min	Max
$L(\text{nH})$	0.1	70
$\text{OD}(\mu\text{m})$	100	400
n	1	20
s/w	0.02	3
ρ	0.03	0.95

Verified by measurements (75) and 3-D field solver simulations (19,000)

TRANSIMPEDANCE STAGE



- Input current drive
- Cascode stage
- On-chip shunt-peaking
- Feedback

DESIGN METHODOLOGY

1. Design and optimize transimpedance stage without shunt peaking
2. Transistor current determines conductor width, w
3. Lithography sets spacing, s
4. Choose n and AD to realize desired L while minimizing parasitic capacitance and area
5. Increase transimpedance resistance, R_f

OPTIMIZATION VIA GEOMETRIC PROGRAMMING

- **Simultaneous optimization of active and passive components**
- **Global Optimum or Proof of Infeasibility**

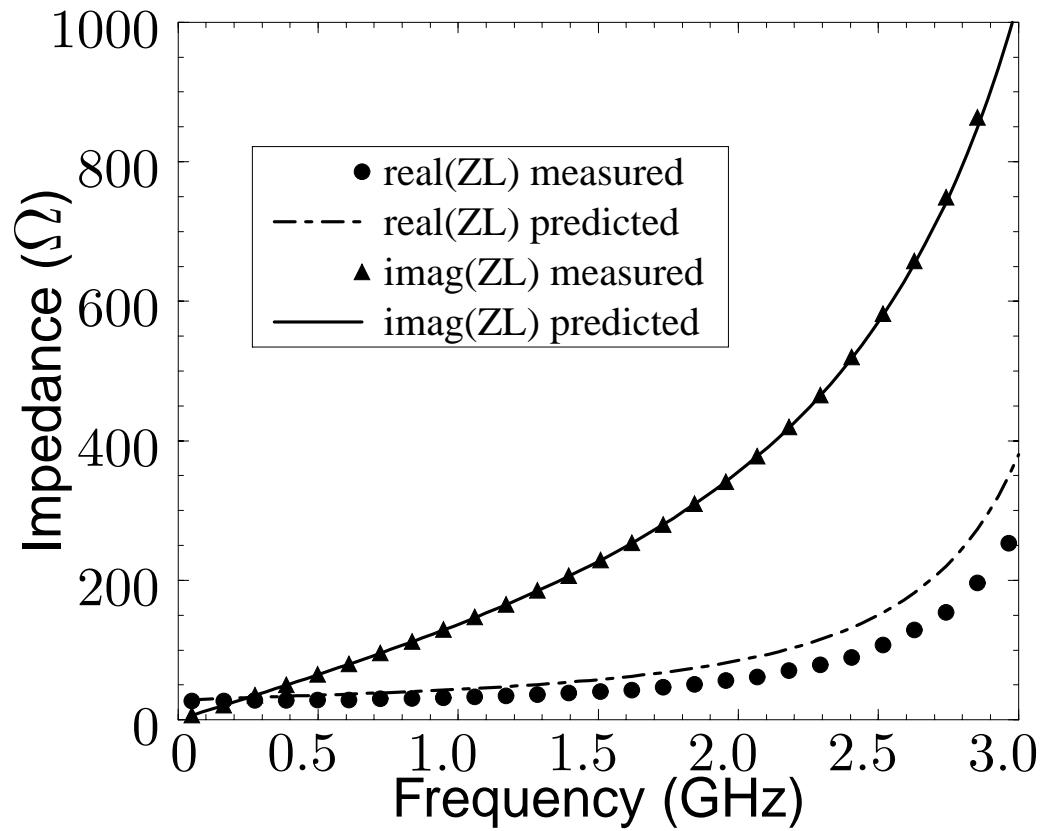
DAC99, Session 54.3 (June 24, 1999):

Optimization of Inductor Circuits via Geometric Programming

Maria del Mar Hershenson, Sunderarajan S. Mohan

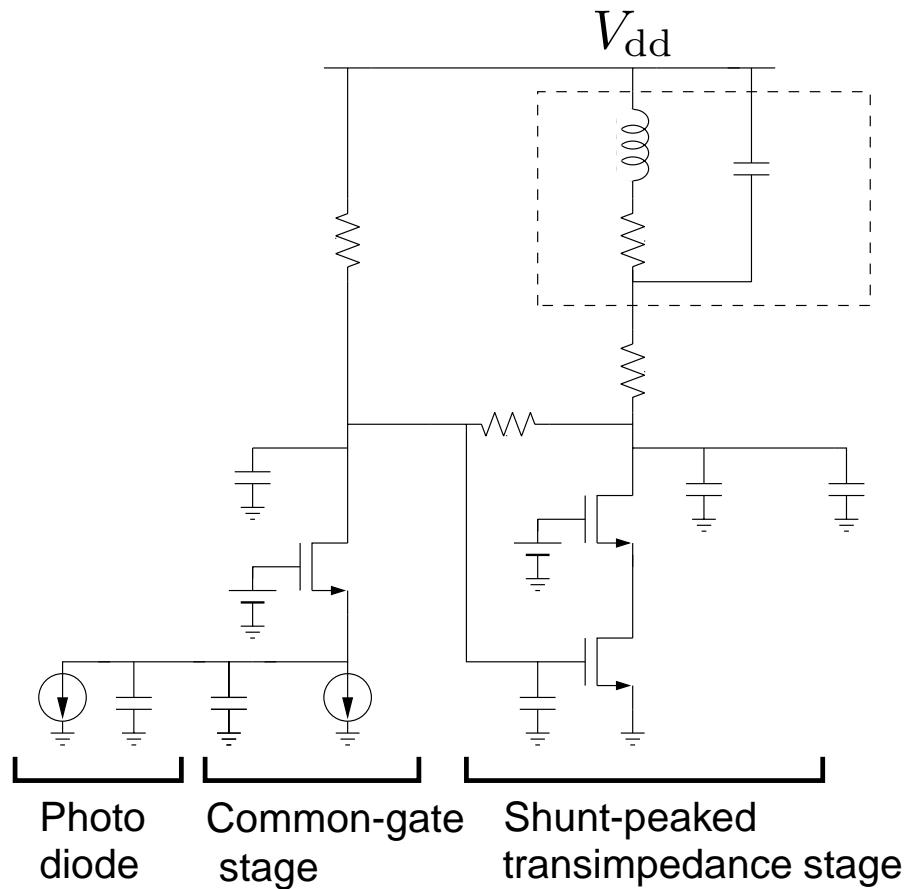
Stephen P. Boyd and Thomas H. Lee

EXPERIMENTAL VERIFICATION OF INDUCTOR



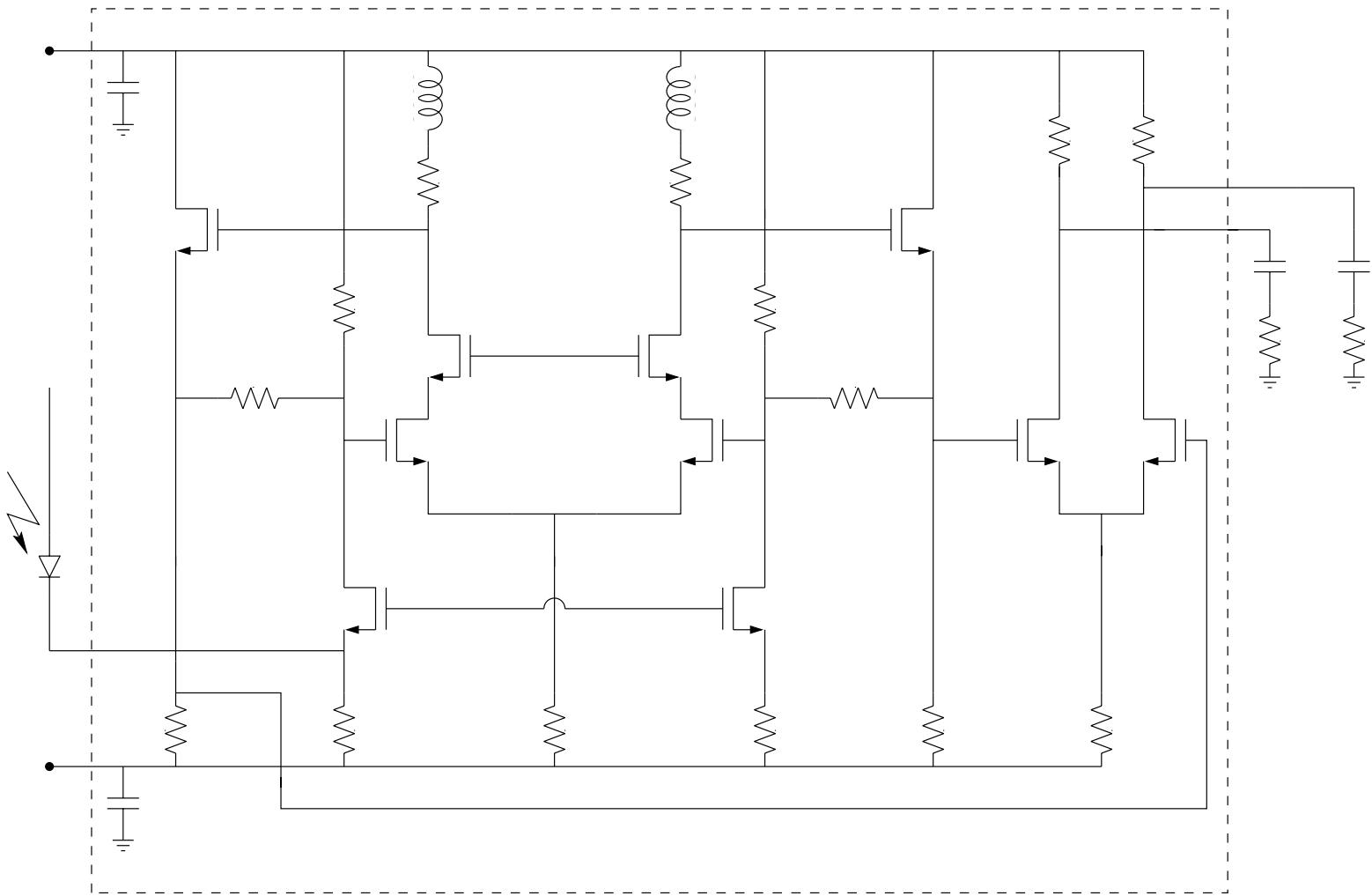
- $OD = 180\mu m$
- $w = 3.2\mu m$
- $s = 2.1\mu m$
- $n = 11.75$
- $L_{meas} = 20.5\text{nH}$
- $L_{pred} = 20.3\text{nH}$

COMMON-GATE STAGE



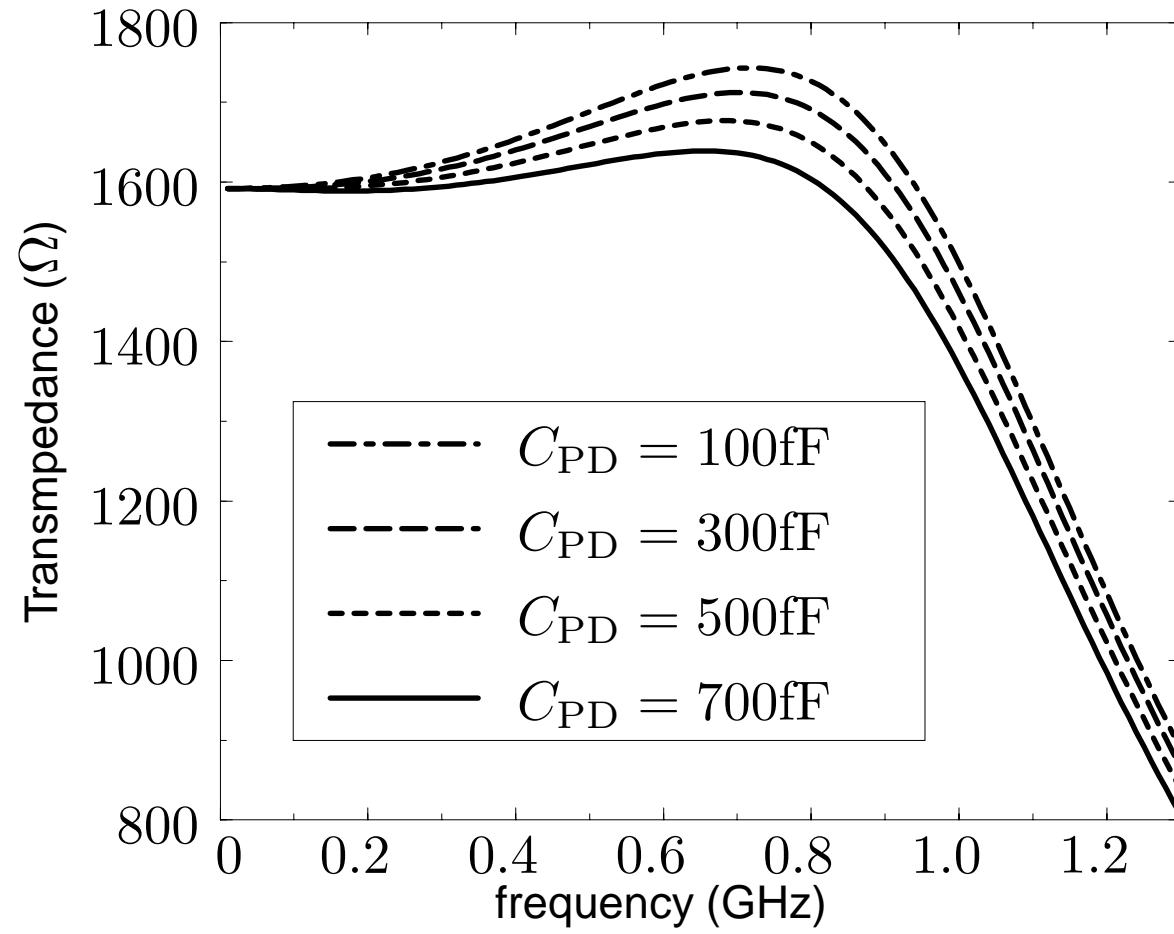
- Decouple sensitive feedback node from external capacitances
- Realize higher transimpedance
- Extra power
- Additional noise terms
- Junction capacitances degrade noise at high frequency

DIFFERENTIAL PREAMPLIFIER

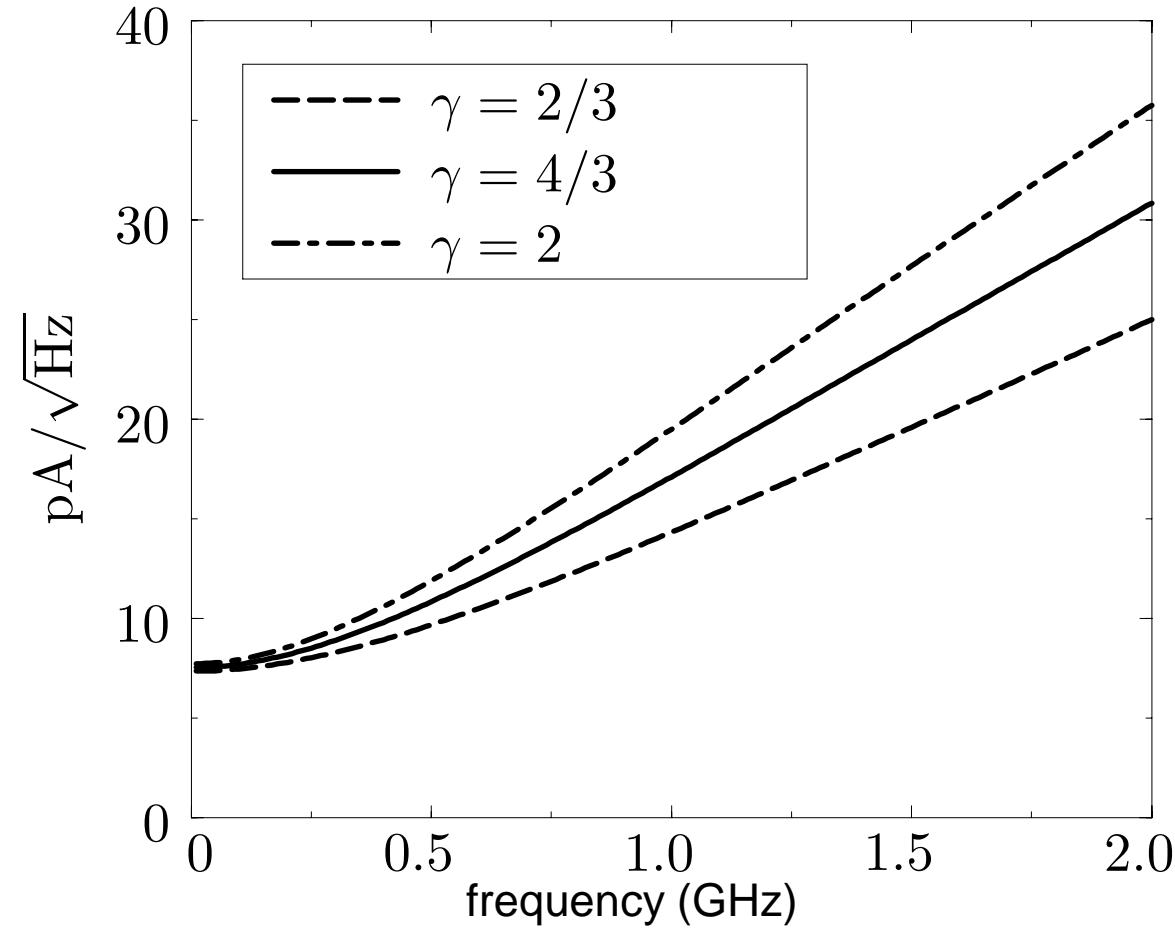


S. S. Mohan, "A 2.125 Gbaud 1.6k Ω Transimpedance Preamplifier in 0.5 μ m CMOS," CICC
May 1999.

TRANSIMPEDANCE BANDWIDTH

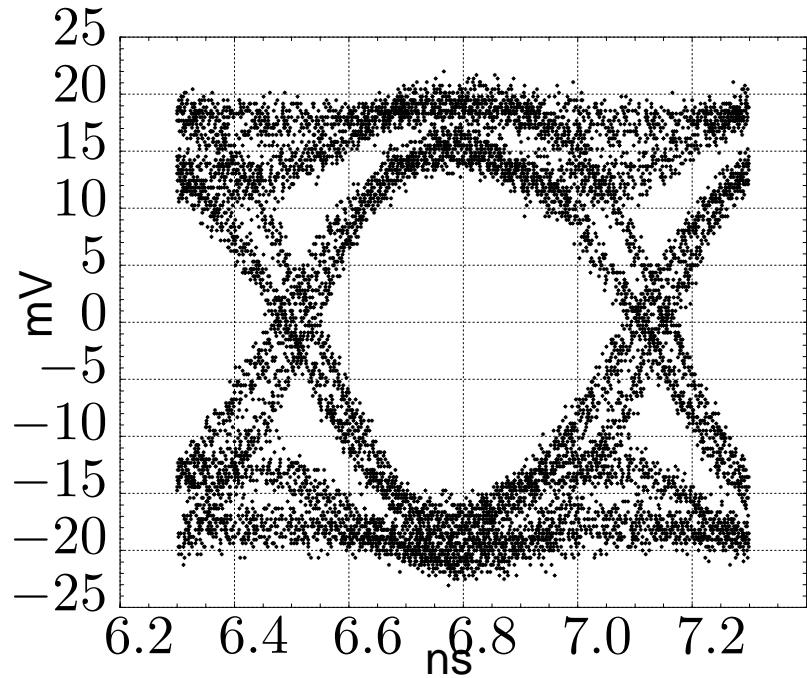


INPUT REFERRED CURRENT NOISE DENSITY

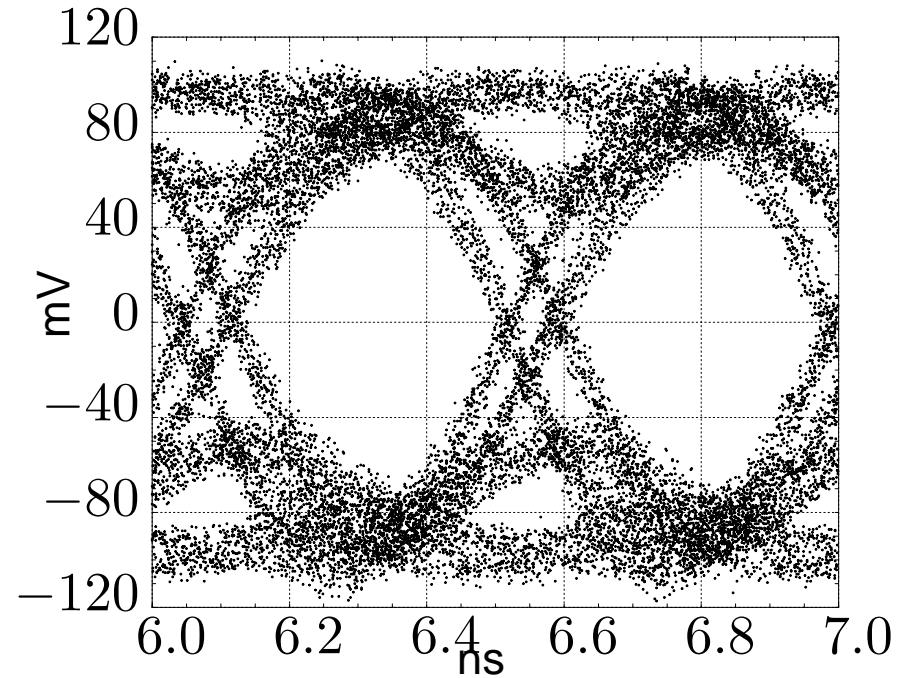


EYE DIAGRAM

1.6 Gb/s



2.1 Gb/s



PERFORMANCE SUMMARY

Transimpedance (small-signal)	1600 Ω (differential) 800 Ω (single-ended)
Bandwidth (3dB)	1.2GHz
Max. photodiode capacitance	0.6pF
Max. input current	1.0mA
Simulated input noise current	0.6 μ A
Max. output voltage swing (50 Ω load at each output)	1.0V _{pp} (differential) 0.5V _{pp} (single-ended)
Power consumption	115mW (core) 110mW (50 Ω driver)
Die area	0.6mm ²
Technology	0.5 μ m CMOS

CONTRIBUTIONS

- Shunt-peaking with optimized on-chip inductor
- Simple accurate expression for inductance
- Common-gate input stage
- CMOS implementation of differential preamplifier

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